

REV	MODIFICATION	DATE	DRAW
A3	Release To ECN20130303	2013.03.12	Seven
A4	Release To ECN20131101	2013.11.06	Michelle
A5	Release To ECN20140404	2014.04.22	Michelle

**RoHS Compliant**

Specification

- 1.Current Rating:2A AC/DC
- 2.Voltage Rating:250V AC/DC
- 3.Contact Resistance:20mΩ Max.
- 4.Insulation Resistance:1000MΩ Min. At DC 500V
- 5.Dielectric Withstanding Voltage:AC 1000V/Minute
- 6.Operating Temp.:−25°C~+85°C

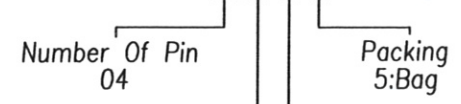
Material:

- 1.Housing:High Temperature Thermoplastic UL94V-0
- 2.Contact Pin:Copper Alloy SQ. Pin 0.64mm

Finish:

- 1.Housing:Natural
- 2.Contact Pin:Bright Tin Plated Over Nickel

Part No.: ADO4150 04 1 1 5 2



Housing Material: 1:PA66+GF UL94V-0 Natural  
Plating: 1:Bright Tin Plated Over Nickel.



		<b>金上達科技股份有限公司</b> <b>GOLDENSUND TECHNOLOGY CO.,LTD</b>					
		TITLE: Wire To Board Wafer 2.54mm 180° DIP With Post					
TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ.		PART NO. ADO4150041152		DWG NO. ADO4150041152	
.x± 0.35	x.± 2'	APR. C.F.Liao 20140422		UNITS: mm		<b>CUSTOMER DRAWING</b>	
.xx± 0.25	.x'± 1'	CHK. Abel 20140422		SIZE: <b>A4</b>		SCALE 4:1	
.xxx± 0.15	.xx'± 0.5'	DRA. Michelle 20140422		SHEET 1 / 1		REV A5	